



Product data sheet

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Semiconductor



SMA

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.063 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

TYPE NUMBER		SS12	SS13	SS14	SS15	SS16	SS18	SS19	SS110	UNITS
Maximum Recurrent Peak Reverse Voltage		20	30	40	50	60	80	90	100	V
Maximum RMS Voltage		14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage		20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current					•					
See Fig. 1			1.0					А		
Peak Forward Surge Current, 8.3 ms single half sine-wave										
superimposed on rated load (JEDEC method)			30					А		
Maximum Instantaneous Forward Voltage at 1.0A			0.55 0.70			0.85			V	
Maximum DC Reverse Current	Ta=25°C	0.2		mA						
at Rated DC Blocking Voltage	Ta=100°C	10		mA						
Typical Junction Capacitance (Note1)			110						pF	
Typical Thermal Resistance R JA (Note 2)			50					°C/W		
Operating Temperature Range TJ			-65-+125 -65-+150					0	°C	
Storage Temperature Range Tsrc			-65-+150					°C		

NOTES:

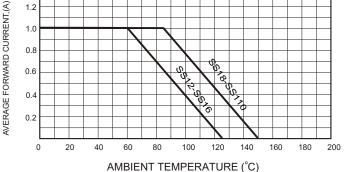
1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

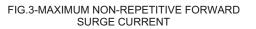
2. Thermal Resistance Junction to Ambient.

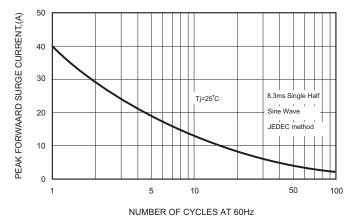


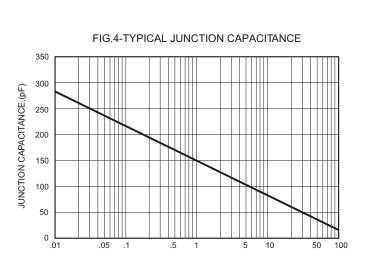












REVERSE VOLTAGE,(V)

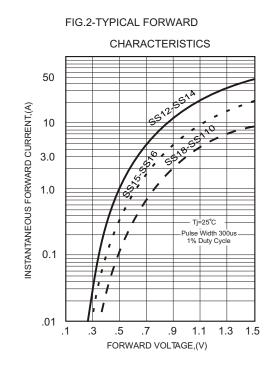


FIG.5 - TYPICAL REVERSE

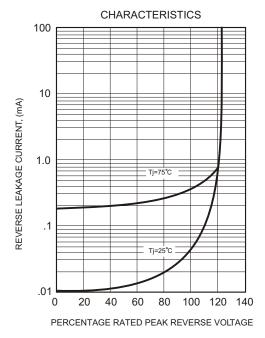
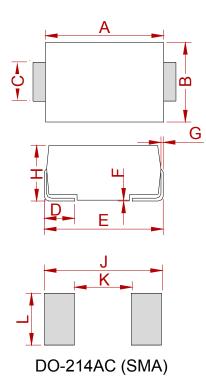


FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE





PACKAGE MECHANICAL DATA



	Dimensions						
Ref.	Millin	neters	Inches				
	Min.	Max.	Min.	Max.			
А	4.25	4.65	0.167	0.183			
В	2.50	2.90	0.098	0.114			
С	1.35	1.65	0.053	0.065			
D	0.76	1.52	0.030	0.060			
Е	4.93	5.28	0.194	0.208			
F	0.051	0.203	0.002	0.008			
G	0.15	0.31	0.006	0.012			
Н	1.98	2.41	0.078	0.095			
J	6.50		0.256				
К		2.30		0.090			
L	1.70		0.067				

REEL SPECIFICATION

P/N	PKG	QTY
SS12 THRU SS110	SMA	2000



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